# Product End-of-Life Disassembly Instructions

## Product Category: Monitors and Displays

### Marketing Name / Model

[List multiple models if applicable.]

- Name / Model #1 HP-W1907
- Name / Model #2
- Name / Model #3
- Name / Model #4
- Name / Model #5

### Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## Items Requiring Selective Treatment

1. **Items listed below are classified as requiring selective treatment.**
2. **Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.**

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>4</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>3</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>SCREW DRIVER (PHILLIPS HEAD)</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Hold Cover Off From Display Head
2. Take Screw(*3) Off From Display Head & Remove Stand Base
3. Remove Front Cover Off From Display Head
4. Take Screw(*2) Off From Front Cover & Remove Function Key Board
5. Remove Function key Off From Front Cover
6. Remove Rear Cover Off From Chassis Ass’y
7. Remove Power Botton Off From Rear Cover
8. Take Screw(*4) Off From Rear Cover & Remove Rear Ring
9. Take Screw(*4) Off From Chassis Bracket & Remove Panel
10. Take Screw(x8) Off From Power Board & Interface Board & Remove Chassis Bracket
11. Take screw (x3) off from shielding
12. Remove backline shielding
13. Take Mylar Off from Chassis Bracket
14. Remove Stand Off From Base
15. Remove Rubber Cushion(*2) Off From Stand
16. Remove Tilt Base Column Rear/Front Off From Stand
17. Remove Hinge Off From Stand Bracket
18. Remove Rubber Cushion(*3) Off From Base Bracket
19. Take Screw(*7) Off From Base Bracket
20. Remove Base Top Cover Off Base Bracket
21. Take Screw(*1) Off From Base Bracket

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
External Electric Cables  Dissecting Process

1. Remove Cable From Display Head.

2. Dissecting To Complete.

D-SUB  Power Cord
Audio Cable
1. Remove Hold Cover Off From Display Head

1. Remove Hold Cover.

2. Dissecting To Complete.
1. Take Screw(*3) Off Form Display Head.
2. Take Screw(*3) Off From Display Head & Remove Stand Base
3. Remove Stand Base.
4. Dissecting To Complete.
3. Remove Front Cover Off From Display Head


2. Dissecting To Complete.
4. Take Screw(*2) Off From Front Cover & Remove Function Key Board

1. Remove Connector From Function Key Board.

2. Take Screw(*2) Off Form Front Cover.

3. Remove OSD Key Board.

4. Dissecting To Complete.
5. Remove Function key Off From Front Cover
6. Remove Rear Cover Off From Chassis Ass’y
7. Remove Power Button Off From Rear Cover

1. The Hand Holds Back To Under.
2. Dissecting To Complete.
8. Take Screw(*4) Off From Rear Cover & Remove Rear Ring

1. Take Screw(*4) Off From Rear Cover.
2. The Hand Holds Back To Under.
3. Dissecting To Complete.
9. Take Screw(*4) Off From Chassis Bracket & Remove Panel

1. Take Screw(*4) Off From Chassis Bracket & Remove Speaker.

2. Remove Connector off from Power Board

3. Take Screw(*4) Off From Panel.

4. Remove Connector off from Panel
9. Take Screw(*4) Off From Chassis Bracket & Remove Panel

5. Remove Panel.

6. Dissecting To Complete.
10. Take Screw(x8) Off From Power Board & Interface Board & Remove Chassis Bracket (Printed Circuit Assemblies>10cm**2)

1. Take screw(*4) off from Interface Board.

2. Take screw(*4) off from power board

3. Take screw(*6) off from P.C.B.

4. Remove Connector off from P.C.B
10. Take Screw(x8) Off From Power Board & Interface Board & Remove Chassis Bracket (Printed Circuit Assemblies>10cm**2)

5. Dissecting to complete.
11. Take screw (x3) off from shielding

12. Remove backline shielding
LCD PANEL EXPLODE

1. Original condition
2. Remove plastic shield and screws
3. Remove Top Chassis
4. Remove panel glass
5. Remove Upper mold frame
6. Remove sheets
7. Remove LGP and reflector
8. Remove lamp screw
9. Remove lamp holder from bottom Chassis
10. Separate lamp and lamp holder
13. Take Mylar Off from Chassis Bracket
Electrolytic Capacitors Over 25mm High & Diameter Dissecting Process

1. Heats Up, Dissolved Tin Lead.
2. Takes Down The Capacitor.
3. Dissecting To Complete. (Next Page Have Description)
Electrolytic Capacitors Process Drawing
14. Remove Stand Off From Base

1. The thumb holds back to under.

2. Remove Stand.
15. Remove Rubber Cushion(*2) Off From Stand
16. Remove Tilt Base Column Rear/Front Off From Stand
17. Remove Hinge Off From Stand Bracket
18. Remove Rubber Cushion(*3) Off From Base Bracket
19. Take Screw(*7) Off From Base Bracket
20. Remove Base Top Cover Off Base Bracket
21. Take Screw(*1) Off From Base Bracket